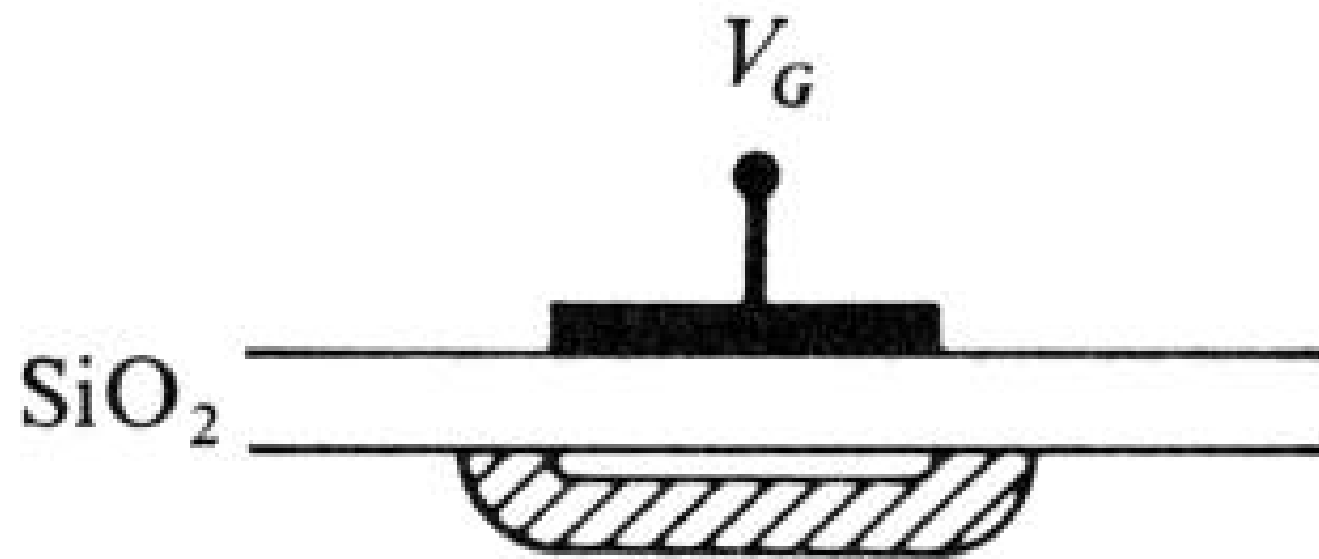
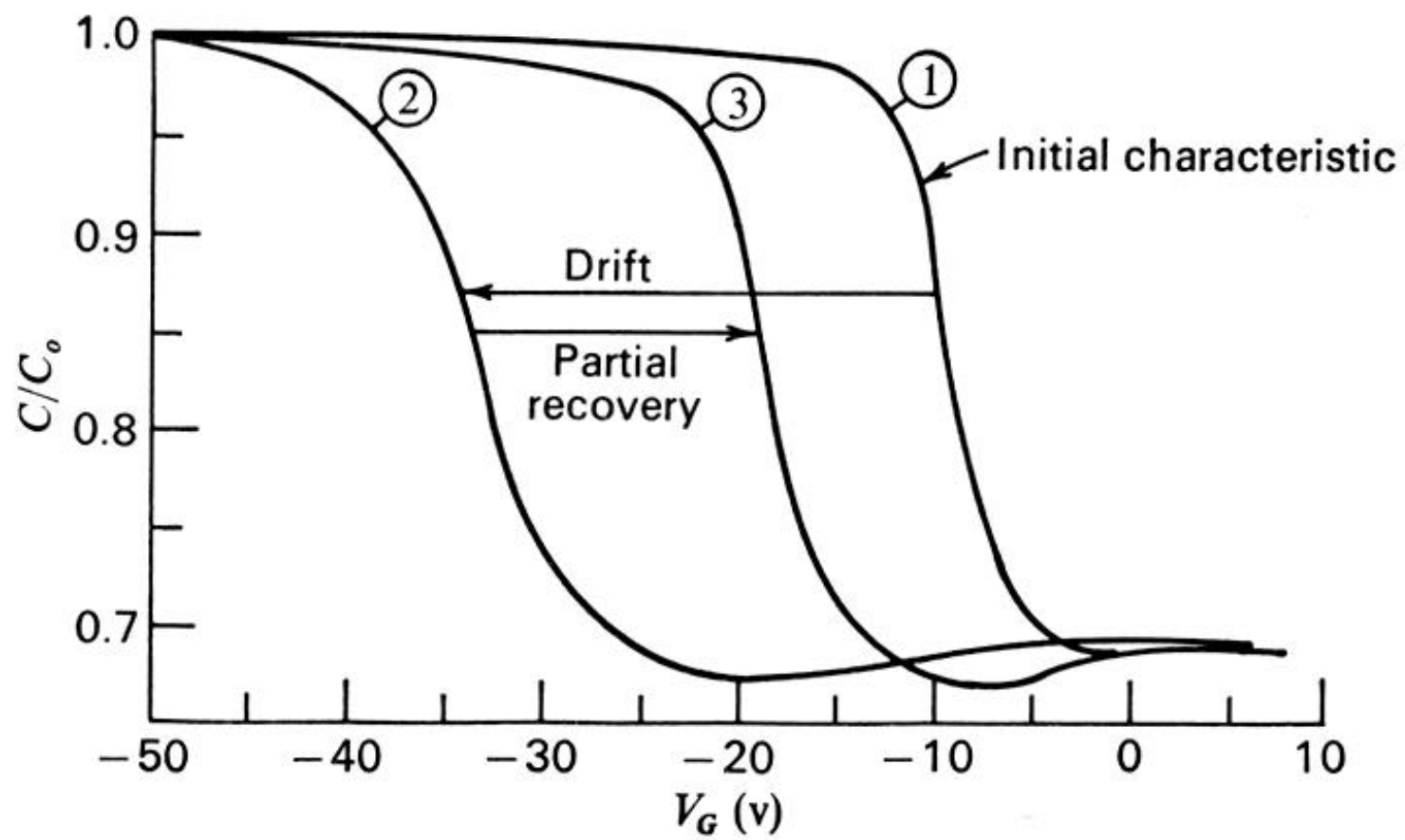


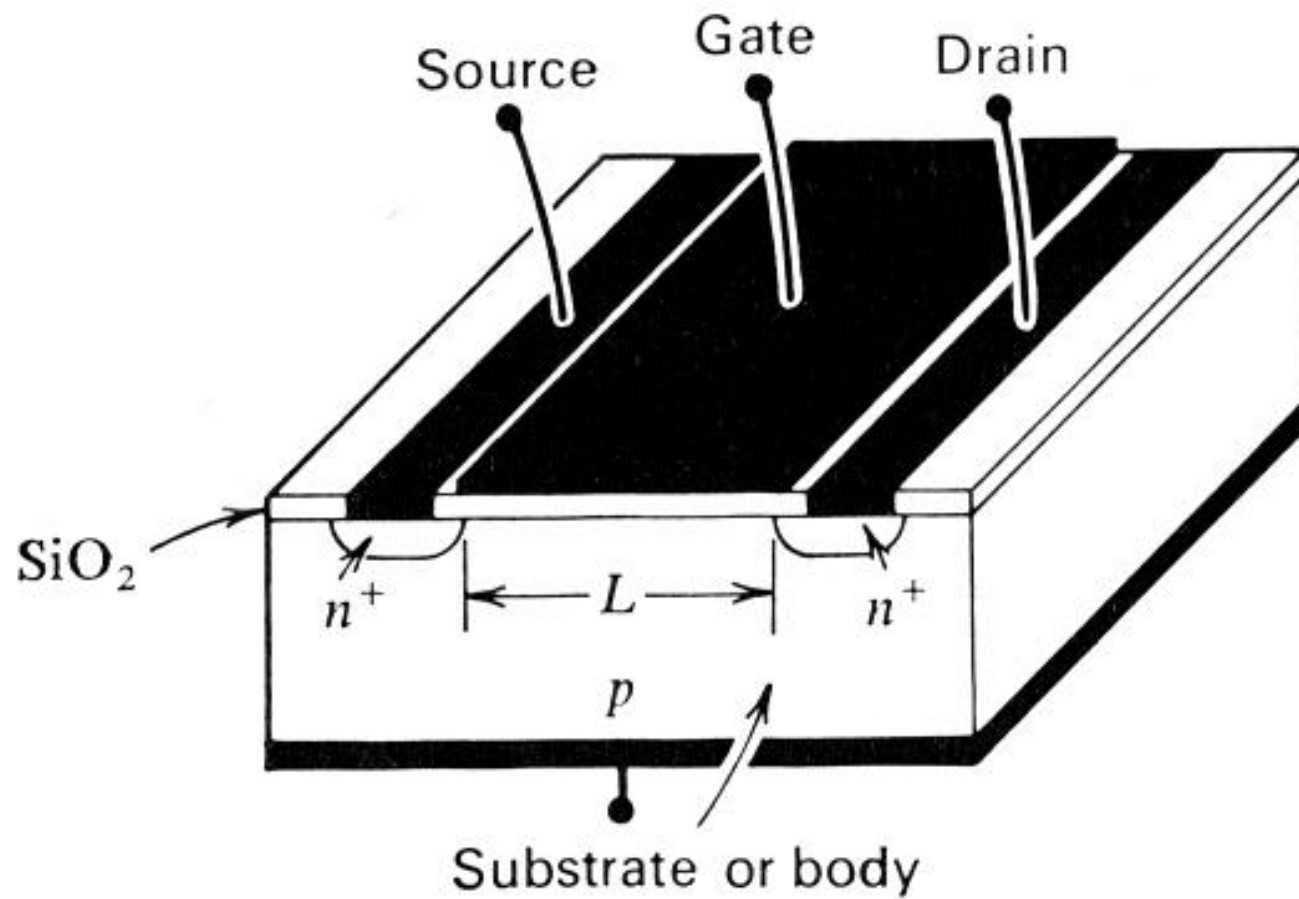
Changing Vectors of Moore's Law

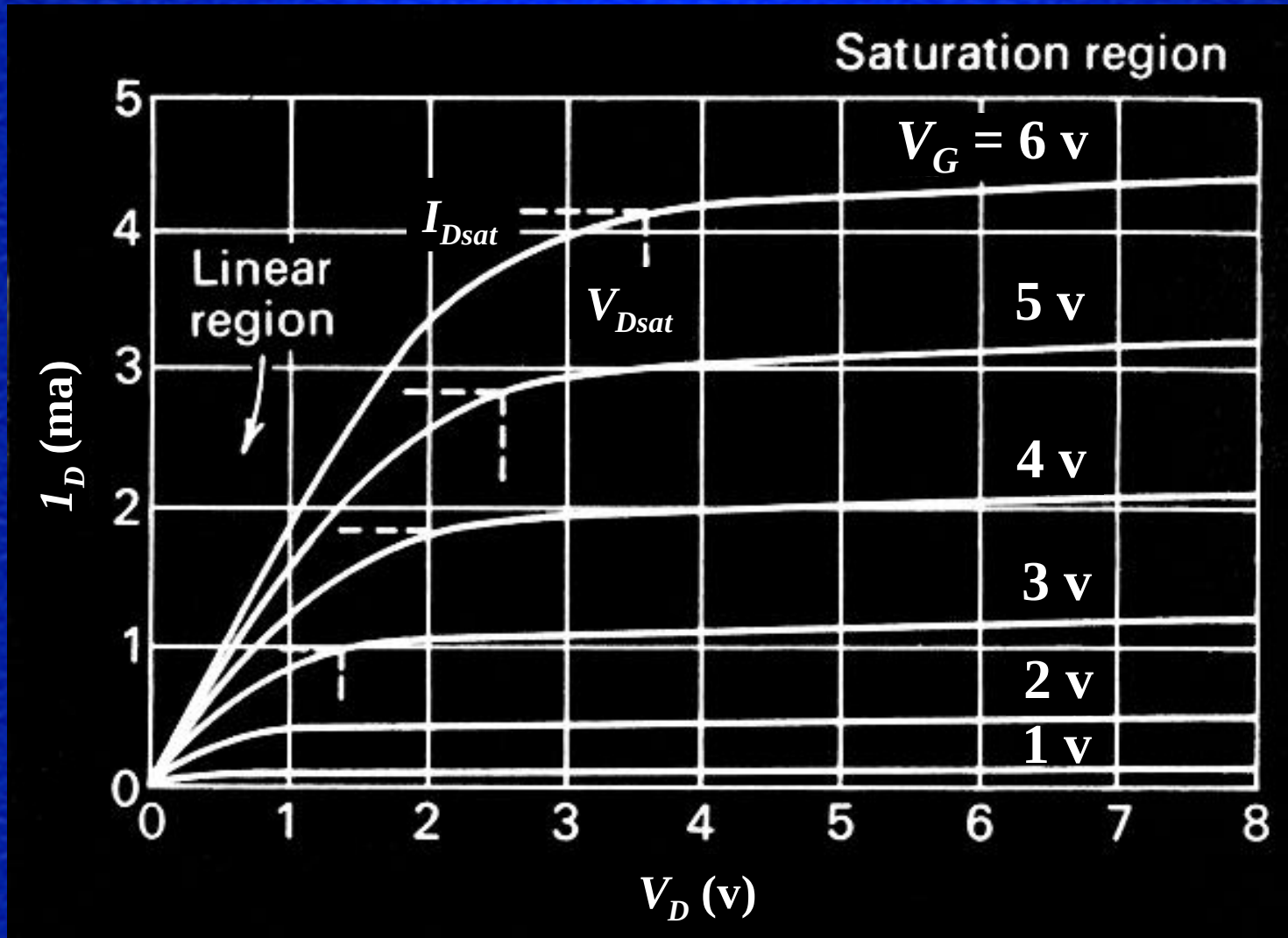
Andy Grove
Chairman of the Board
Intel Corporation

International Electron Devices Meeting
December 10th, 2002









The Gift of Silicon

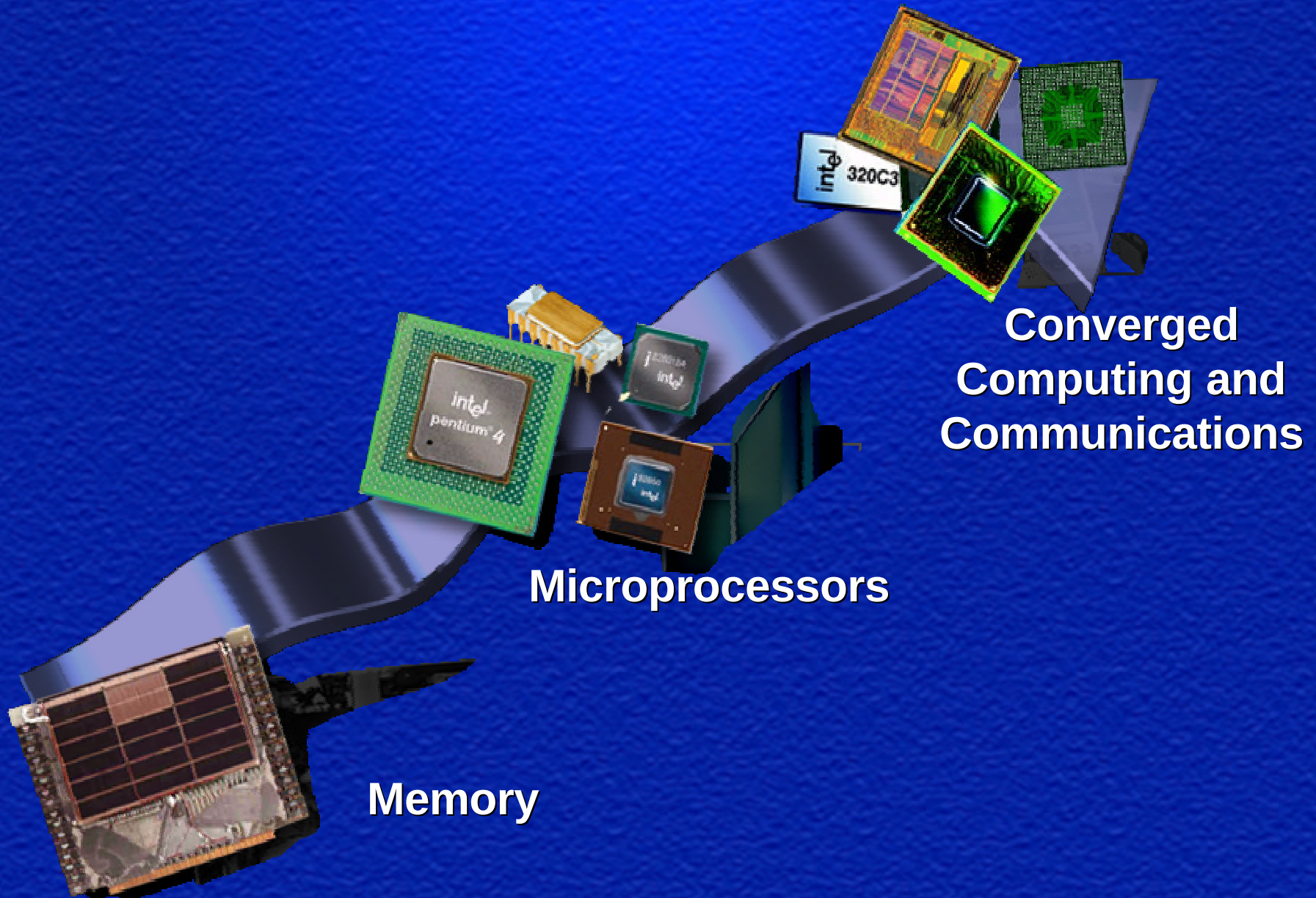
One of the most populous elements

Perfectly mated: Silicon dioxide

Foundation of an industry

Simplicity of MOS transistor fabrication

Silicon is the Engine



Device Integration Gets More Complex

Computational environment spreads

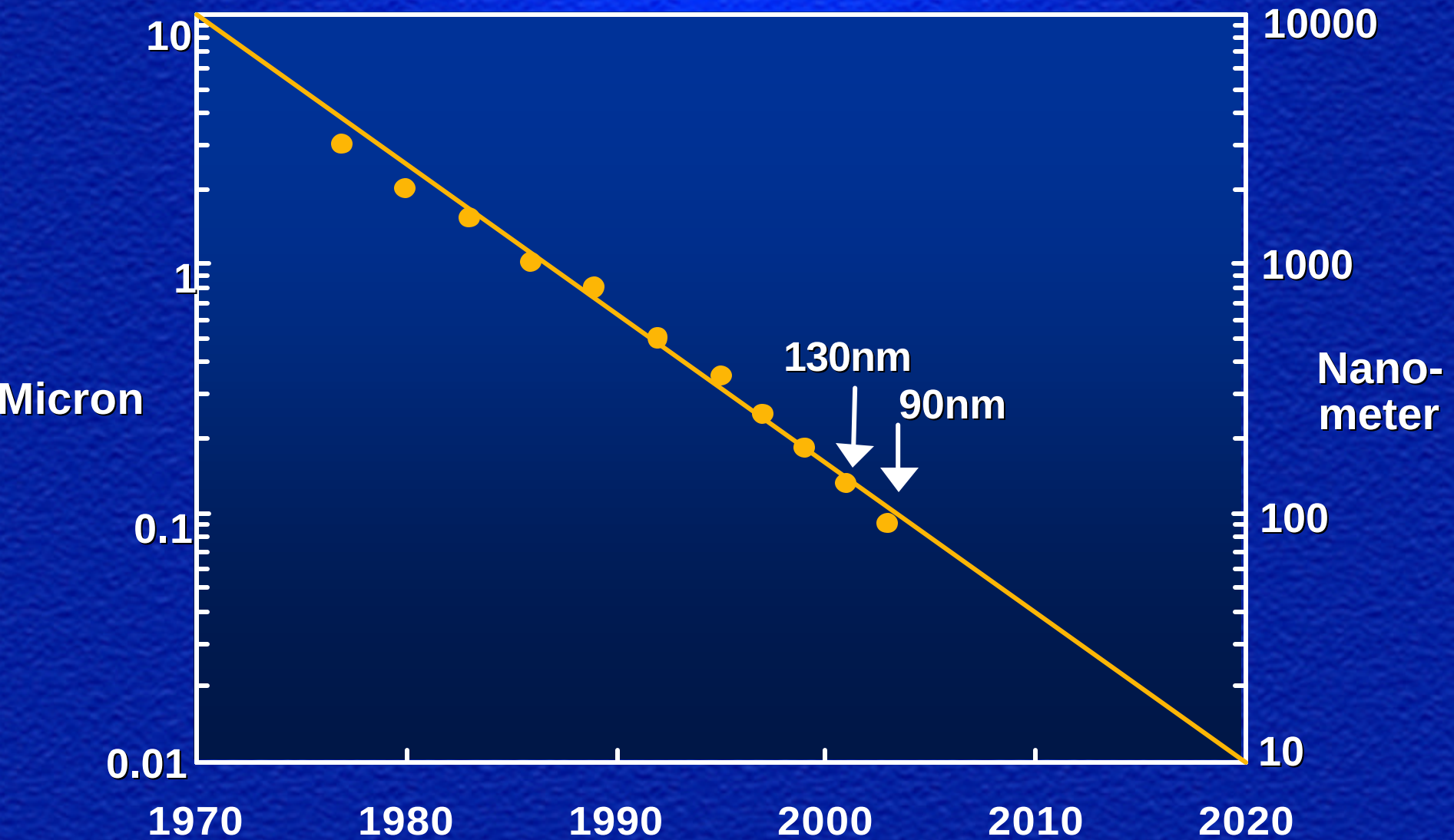
Flash/logic on the same chip

Ubiquitous radios

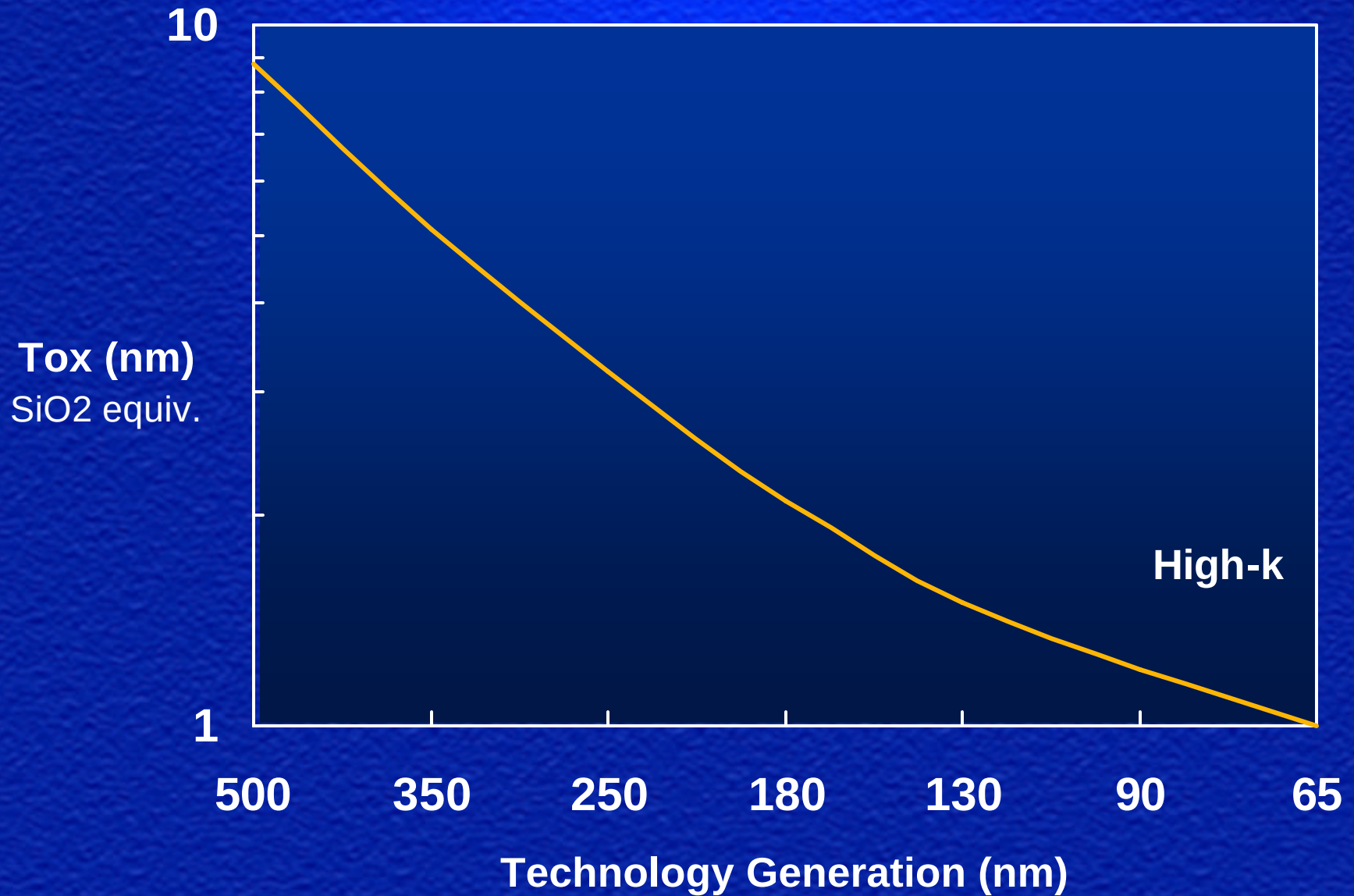
Nano-scale technology

Introduction of new materials

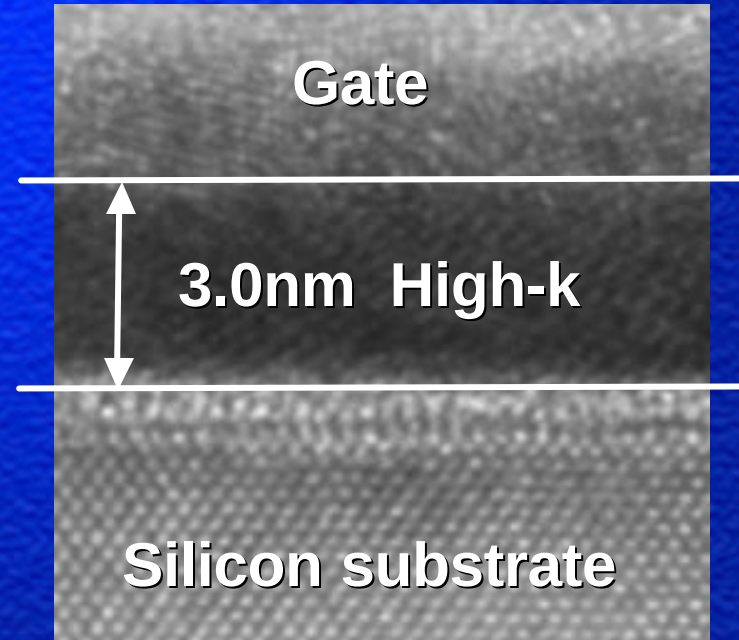
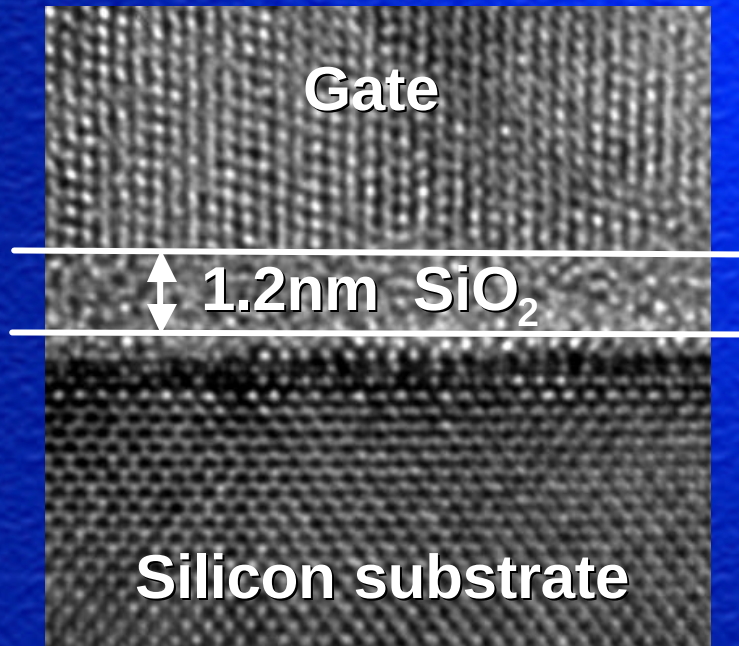
Nominal Feature Size Trends



Gate Oxide Trends



Gate Dielectrics



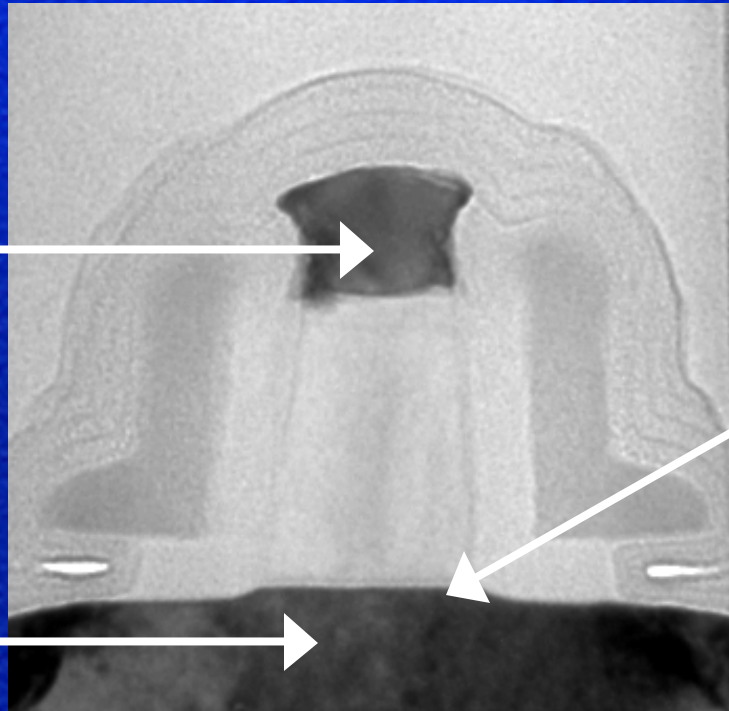
	<u>90nm process</u>	<u>Experimental high-k</u>
Capacitance	1X	1.6X
Leakage	1X	< 0.01X

Integration is the key challenge

New Materials Extend Si Scaling

Gate
New Silicide
material

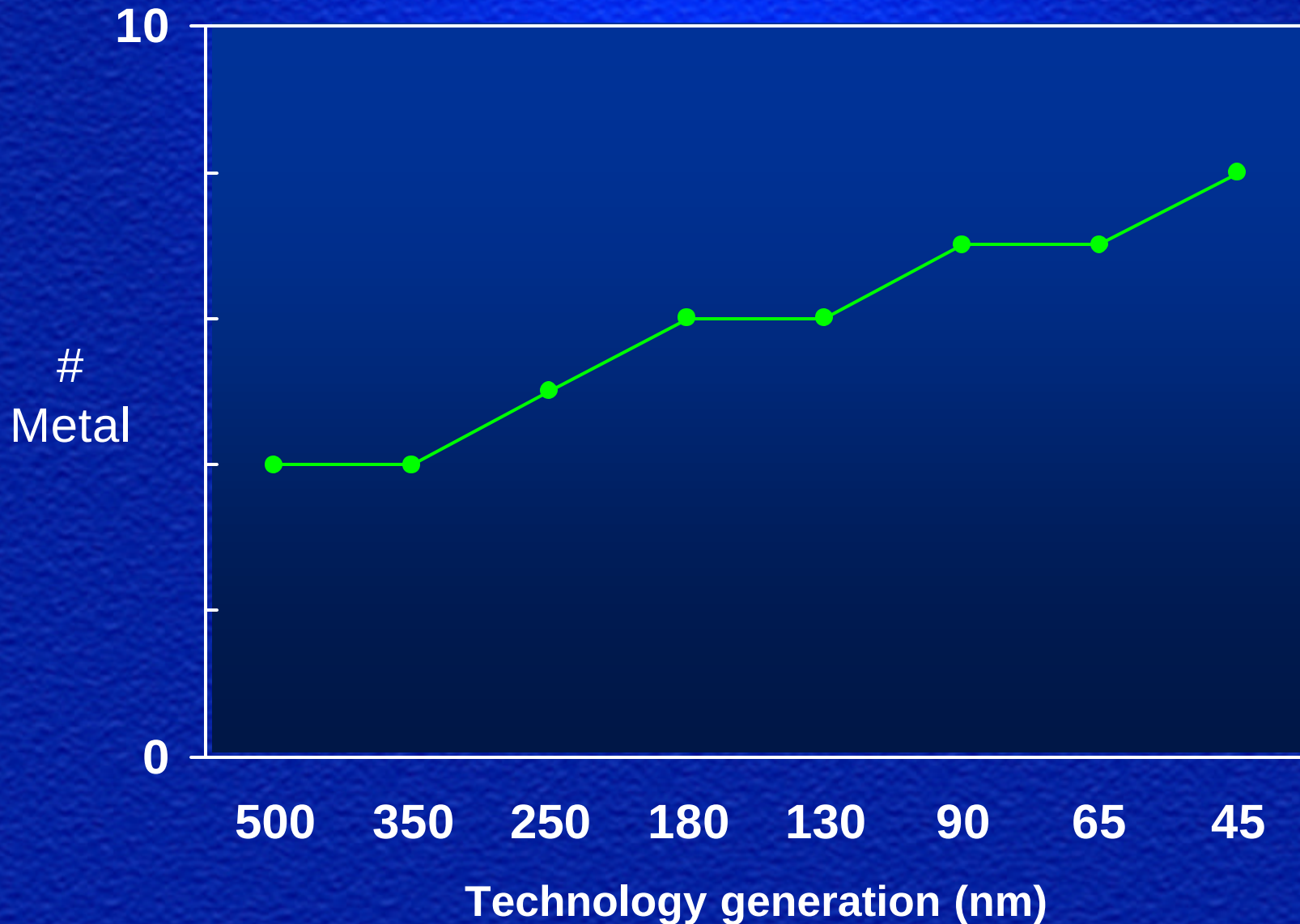
Channel
Strained
silicon



High-k
gate
dielectric

Transistor

Interconnect Trends



New Materials for Interconnects

Changes Made

Metal lines

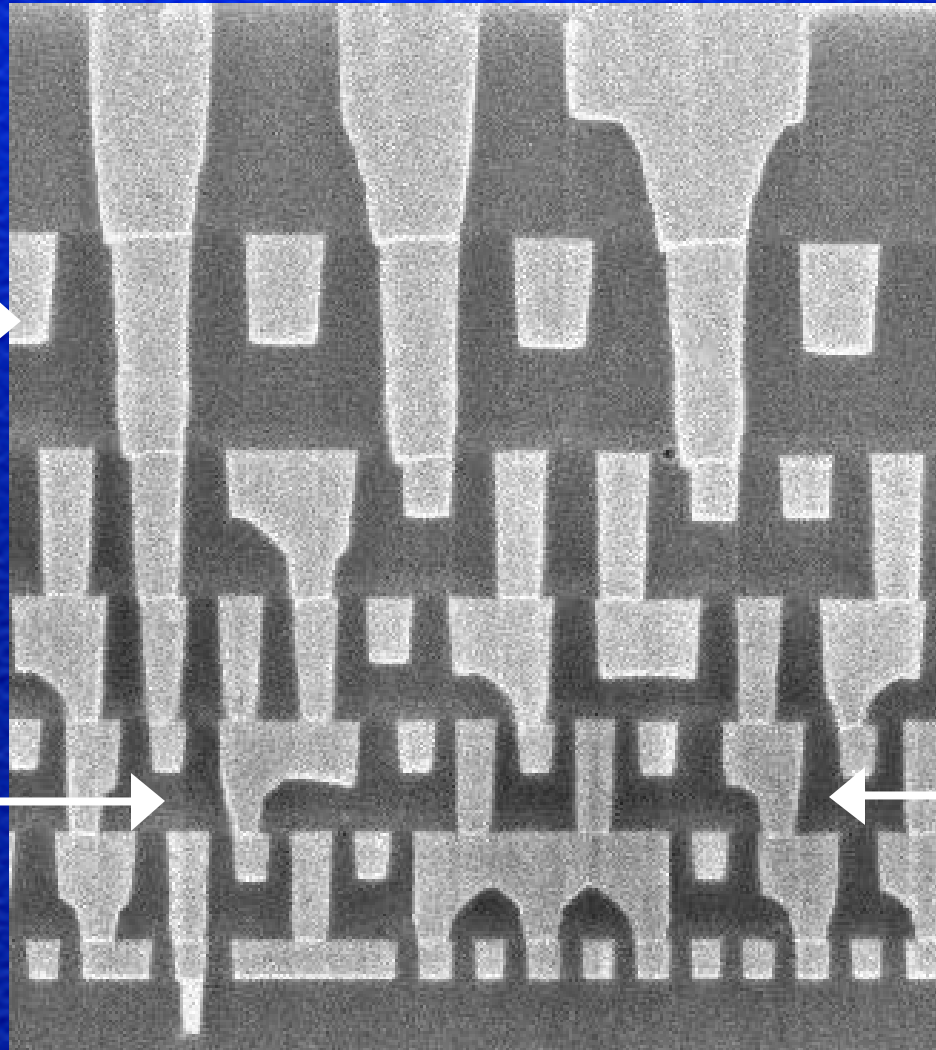
Al → Cu

Insulating dielectric

SiO₂ → SiOF

→ CDO

(low-k)



Future Options

Ultra
Low-k
Dielectric

Interconnects

Number of Materials

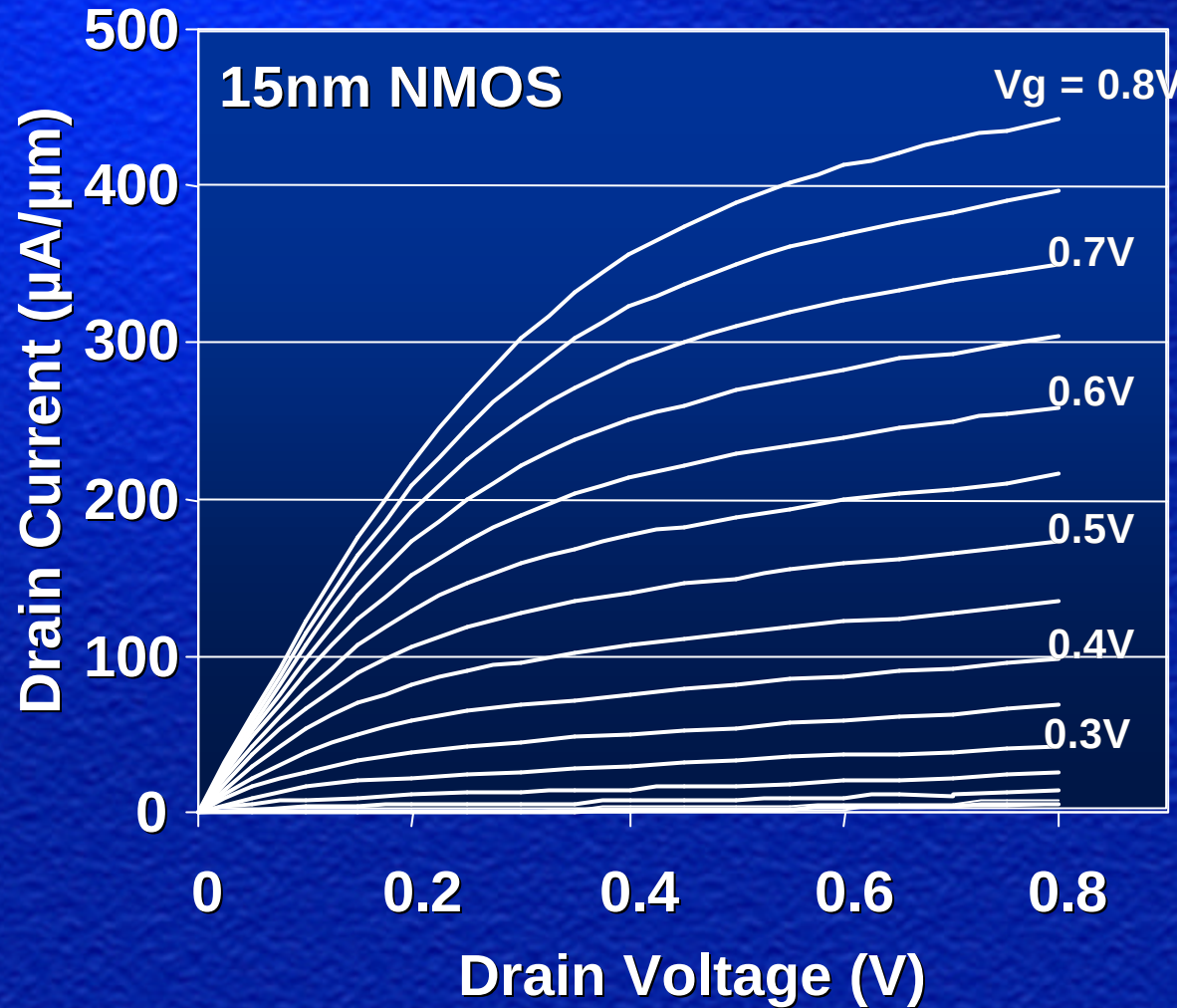
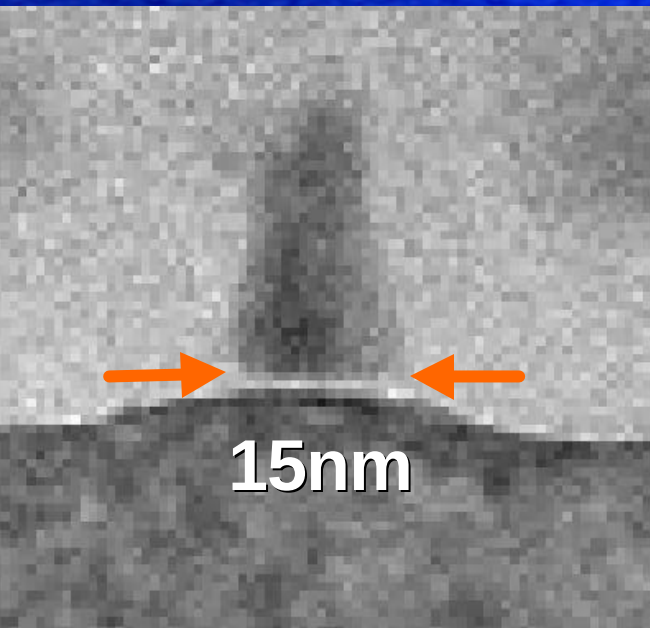
Started

~5

Now

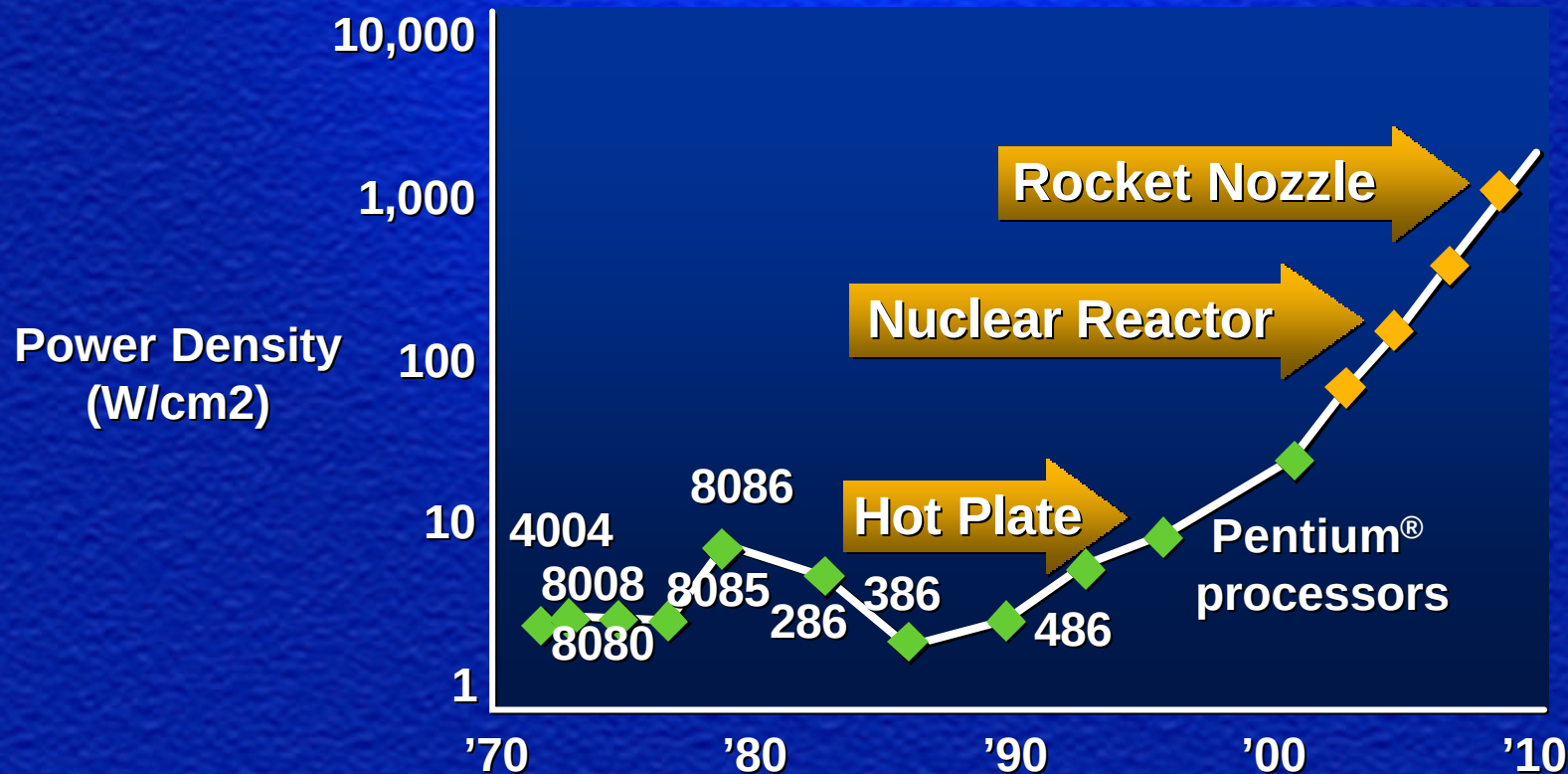
~20

Experimental 15nm Transistor



Problem: High off-current

Power Density Will Get Even Worse



Need to Keep the Junctions Cool

- Performance (Higher Frequency)
- Lower leakage (Exponential)
- Better reliability (Exponential)

Power Trends: Power Leakage

% of Total
Power

40%
35%
30%
25%
20%
15%
10%
5%
0%

Pentium
@ 66 Mhz

Pentium
Pro @ 200
Mhz

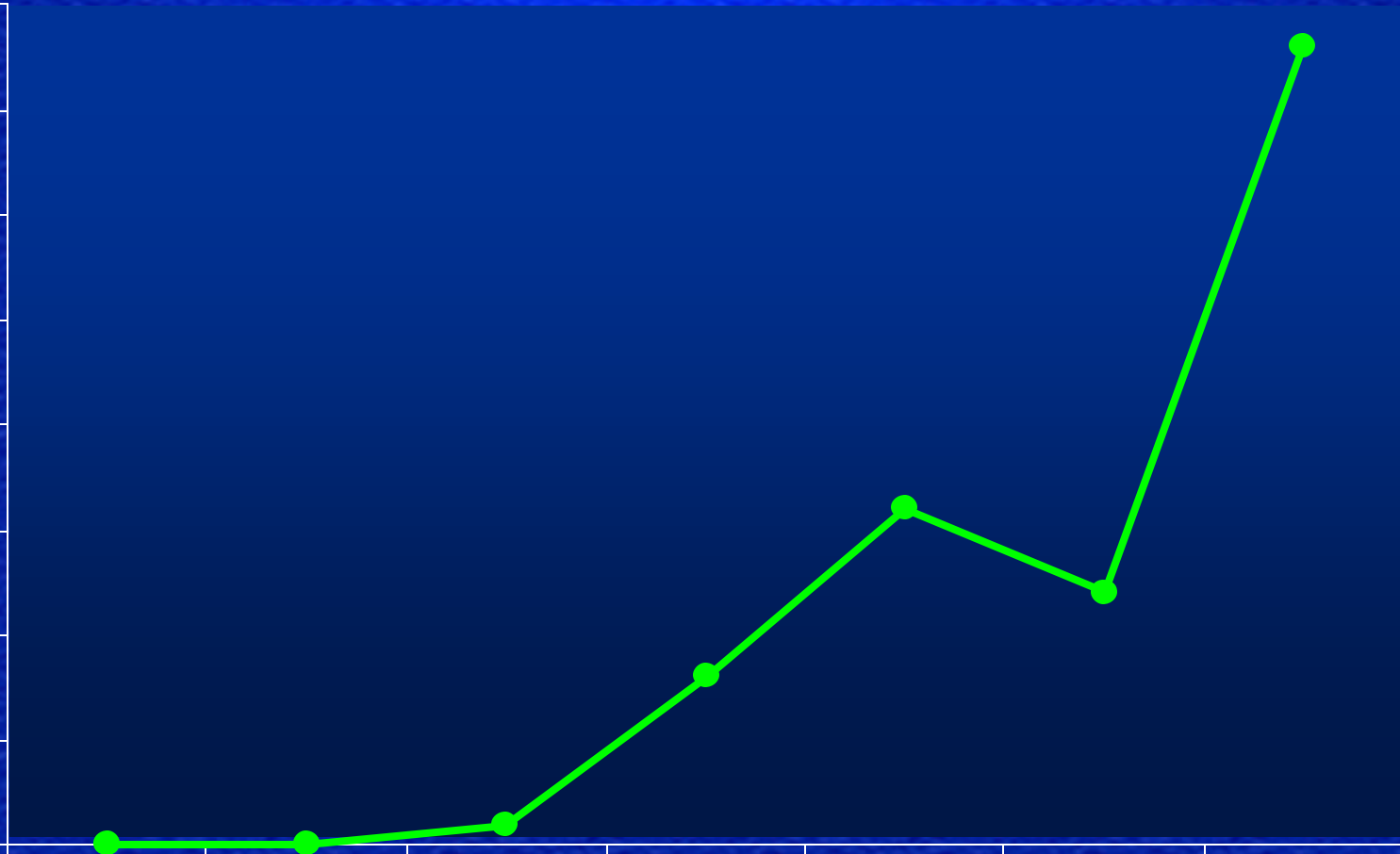
PII @ 333
Mhz

PII @ 650
Mhz

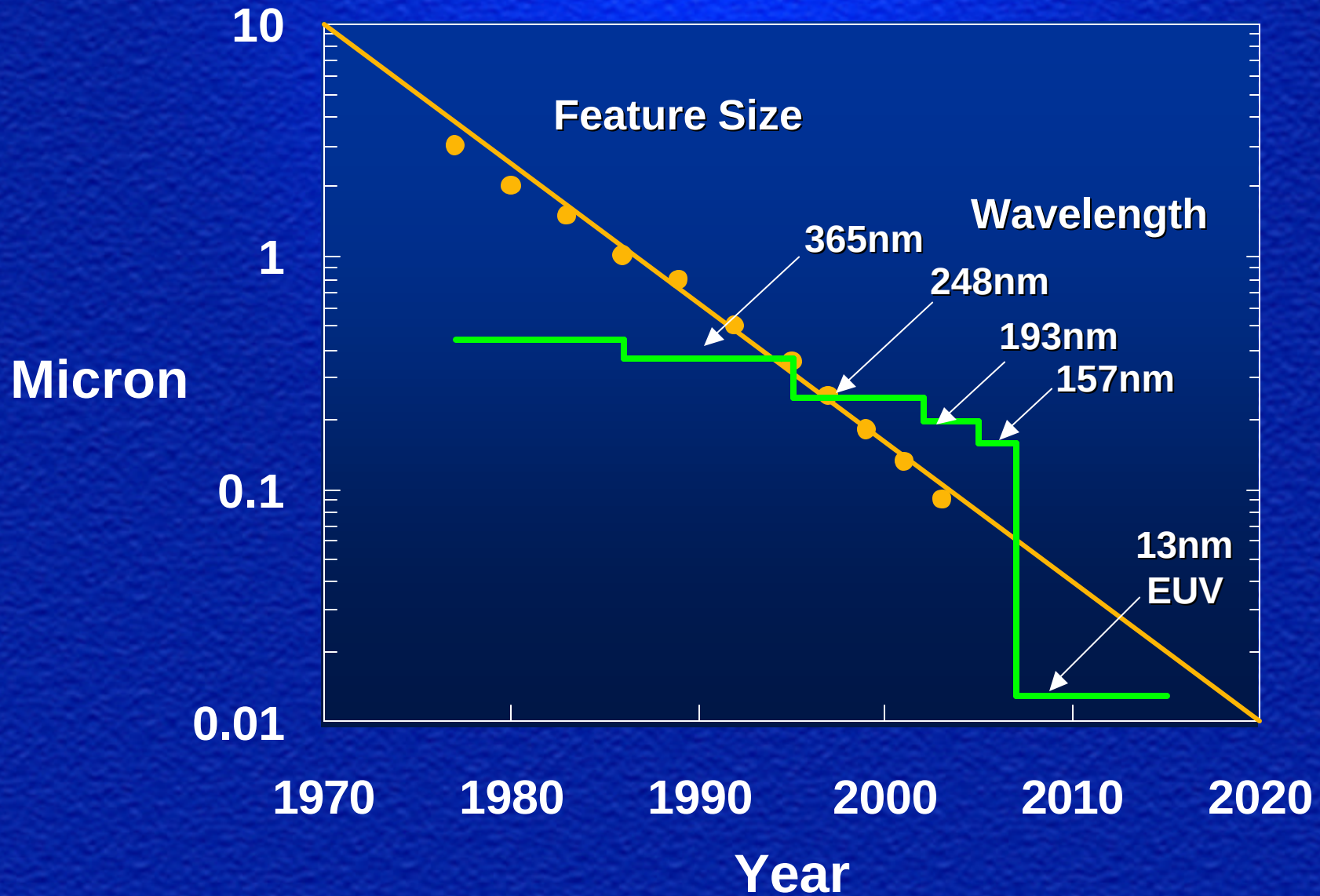
P3 @ 933
Mhz

P4 @ 2
Ghz

P4 @ 3Ghz



Lithography Trend



Minimum Economic Scale

Mid 60's	< \$1M
----------	--------

Mid 70's	\$3M
----------	------

Early 90's	\$1B
------------	------

'02	\$3B
-----	------

2010	\$??B
------	-------

Continuing traditional scaling:

new (nano) frontier

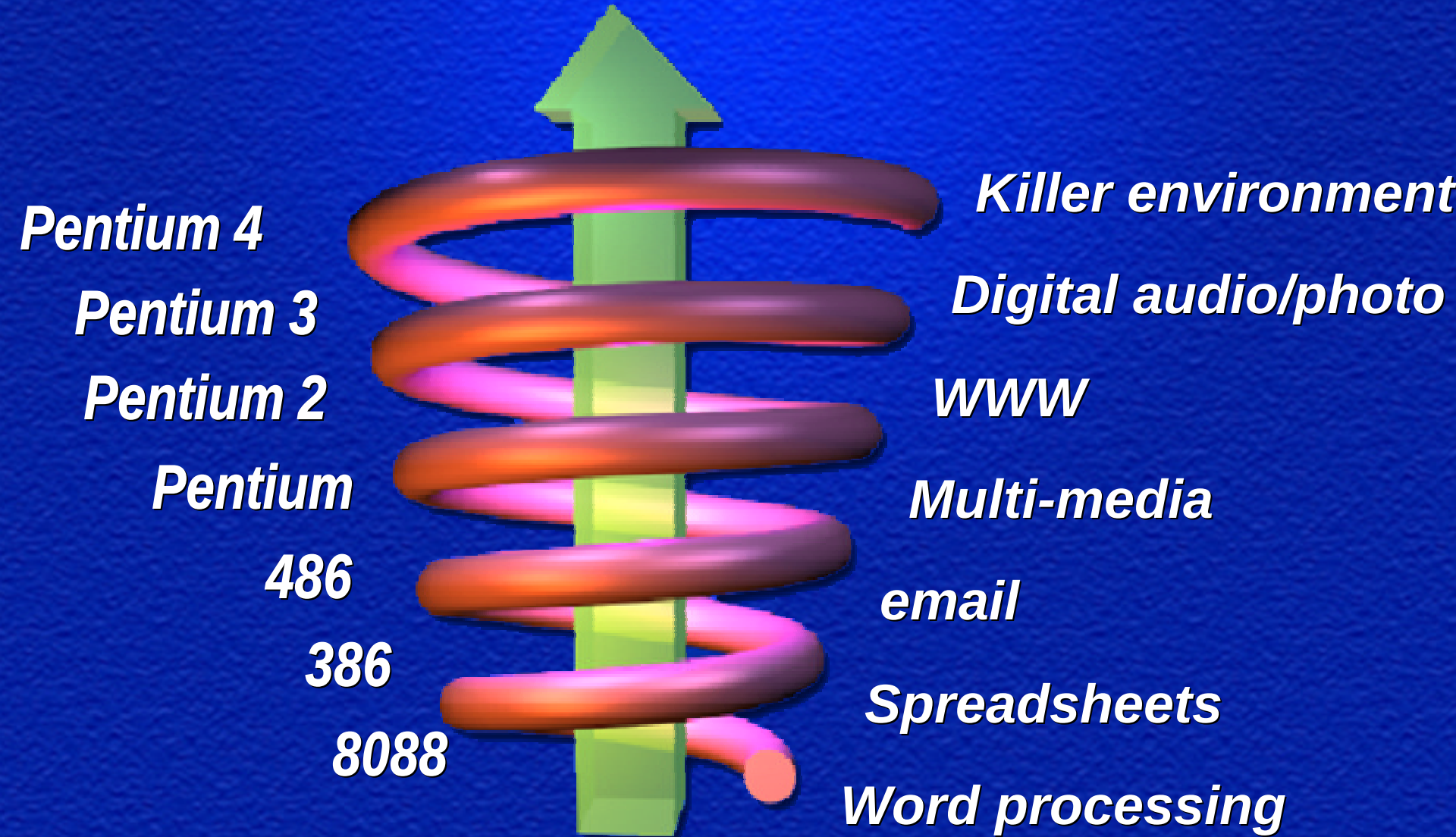
Interconnects: 3rd dimension

Leakage: power limiter!

Transistors & Interconnects: new materials

Cost: minimum economic scale skyrockets

**Silicon devices are the
foundation of the
digital spiral**



The Killer Environment

A complete digital platform

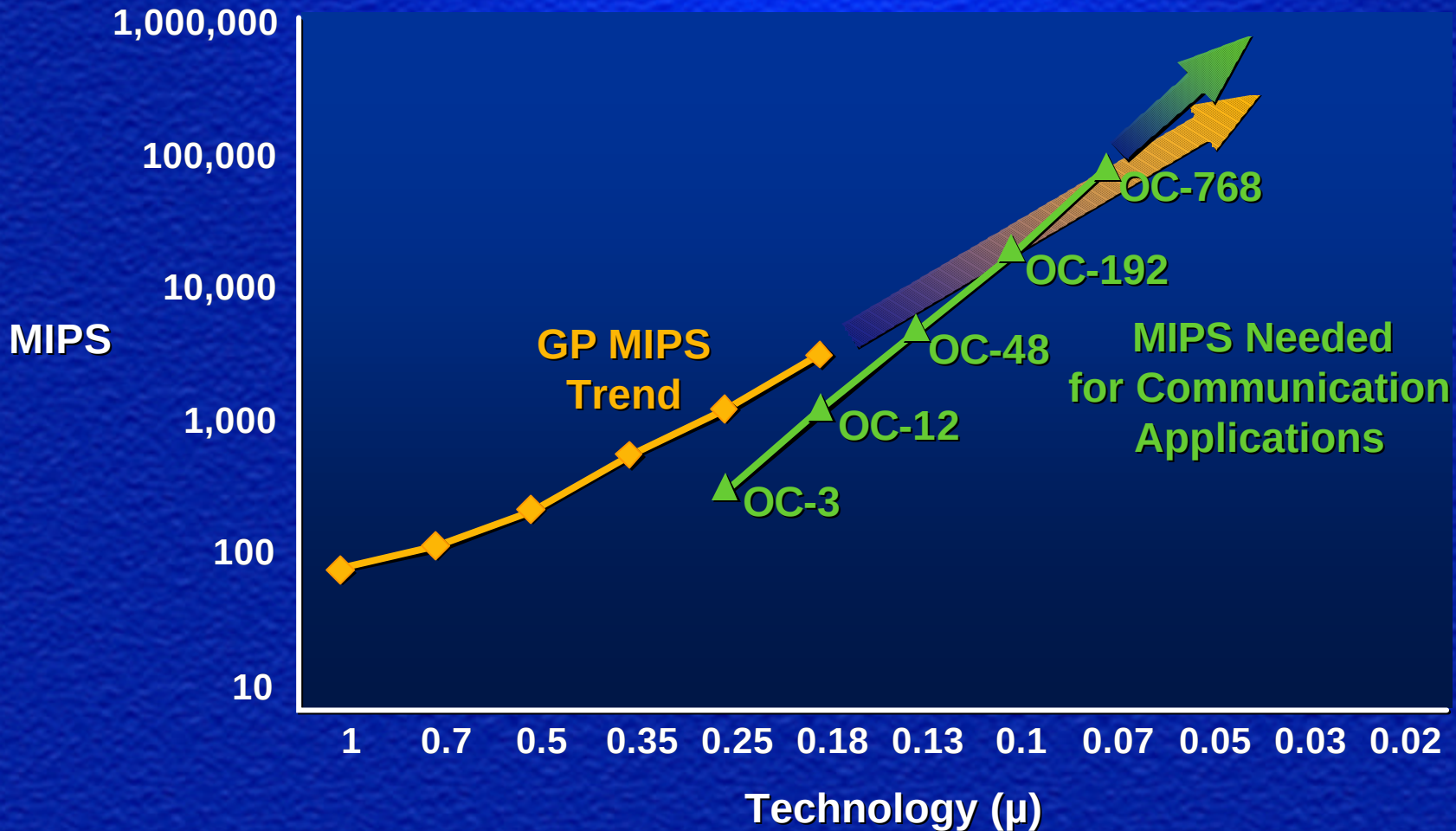
- Virus scanning, security, easy attachments
- Embedded images, clips simultaneously
- Audio, speech
- Network Communication
- Encryption / Decryption
- Media Encode / Decode

*Today's Pentium 4:
3Ghz, 13k MIPS, 55M transistors*

**So what are we going to do with a
billion transistors?**

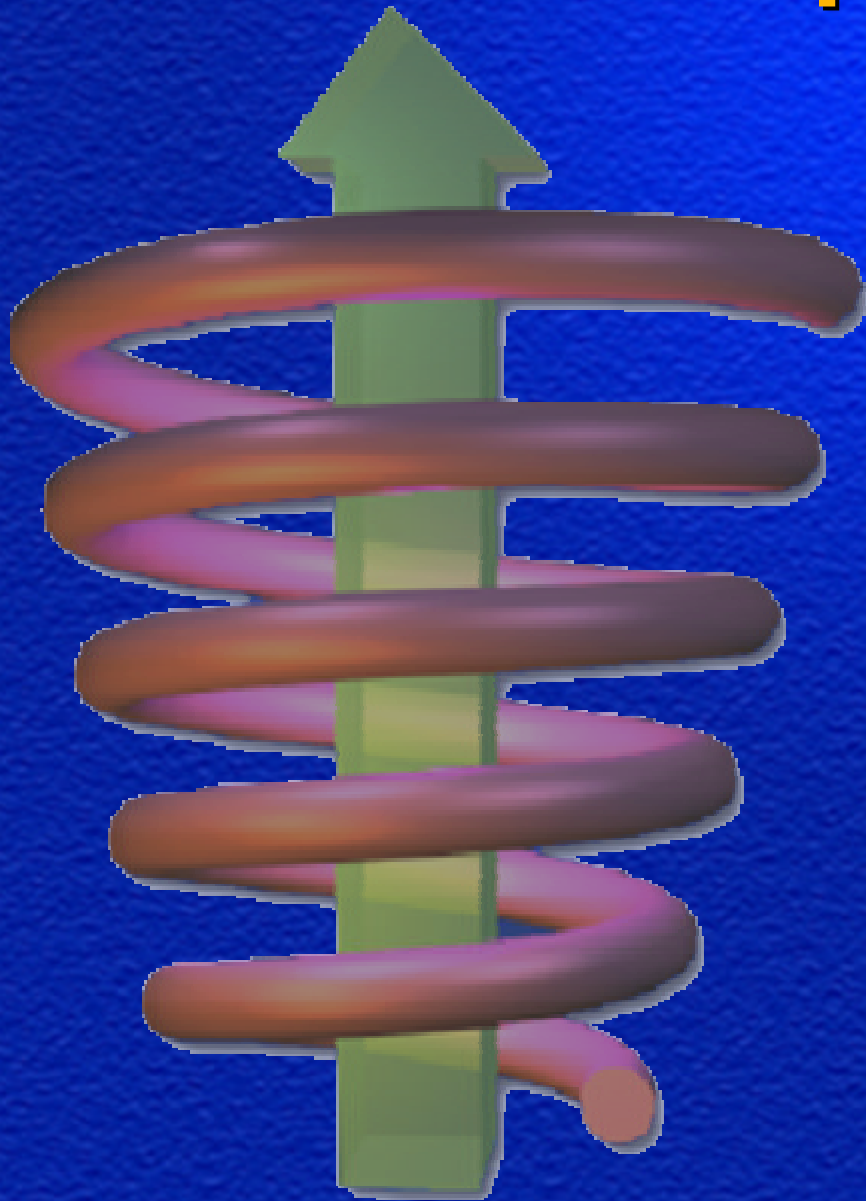
**What is the next revolution of the
digital spiral?**

Communications Applications are Hungry...



...and Could Consume All Available MIPS

As the spiral turns.....



Probabilistic computing

Wireless everything

Natural IO

Killer environment

Wireless Everything

Radios wherever they make sense!

Moore's law applied to spectrum

Foundation of Pervasive computing

**Dependent on more MIPS for better digital
computation & communication**

**The digital spiral
continues**

Enter the next frontier

Processor Power Required

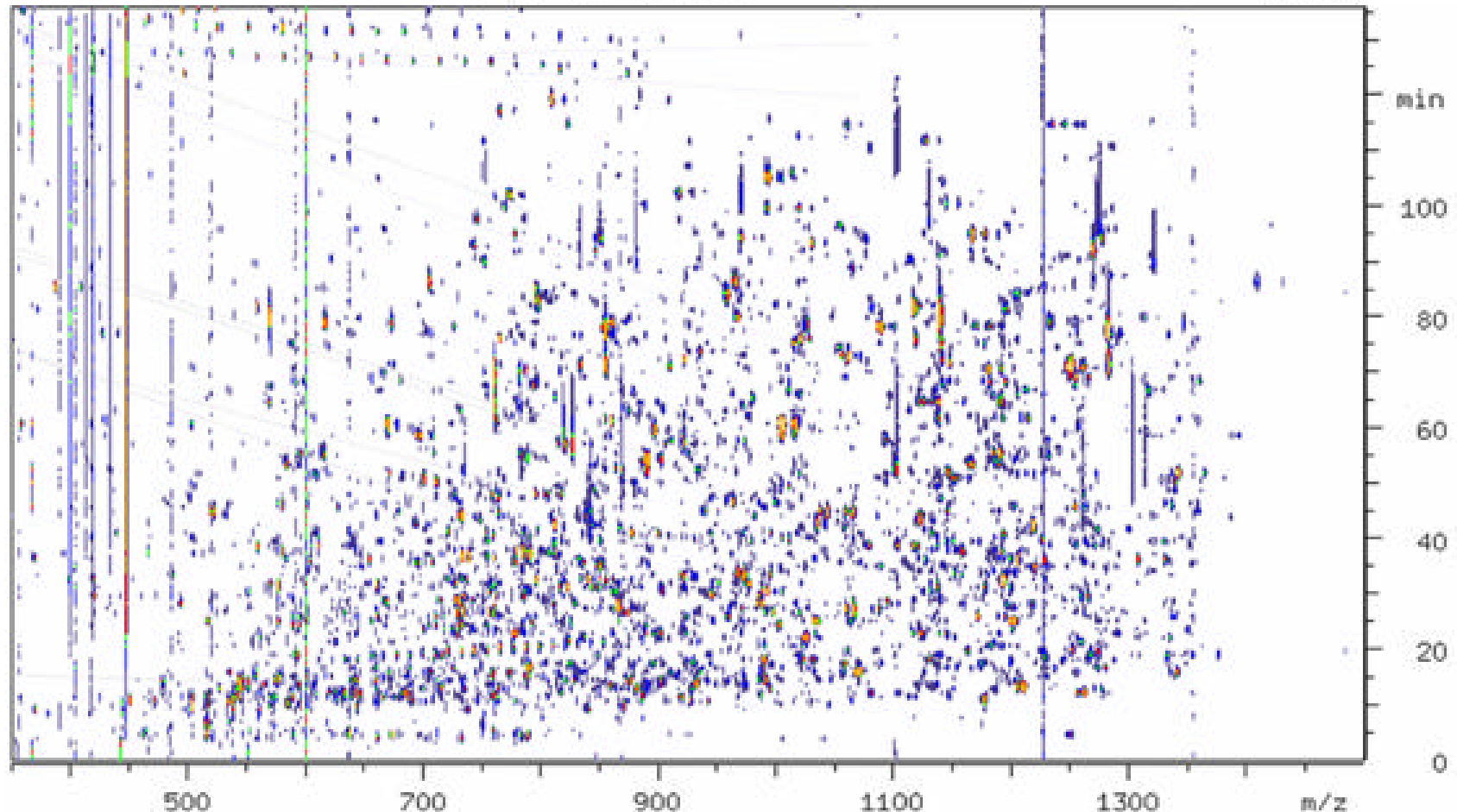
Intel®, Pentium®, 4 processor	1,099 MFLOPS
Speech to Text	1,500 MFLOPS
Natural Language Processing	6,550 MFLOPS
Feature Recognition	11,000 MFLOPS

Drosophila Melanogaster proteome

Drosophila Melanogaster proteome (C:I t=24hrs) from capLC-FTMS

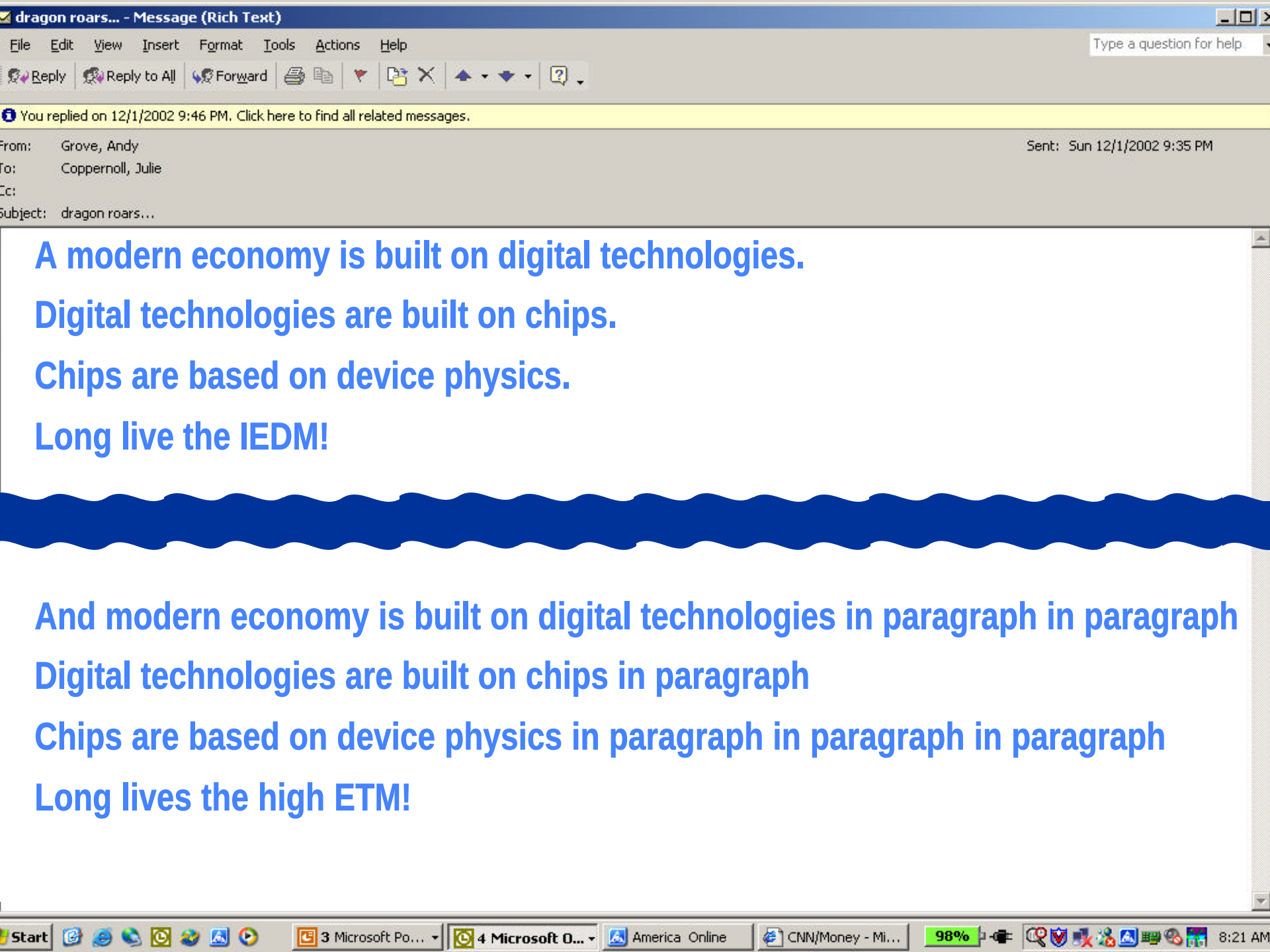
John Tenebris, Katarina Pihlak, Ryan Smith

week 44 (2002)



But first....

Get speech right!



A modern economy is built on digital technologies.

Digital technologies are built on chips.

Chips are based on device physics.

Long live the IEDM!

And modern economy is built on digital technologies in paragraph in paragraph

Digital technologies are built on chips in paragraph

Chips are based on device physics in paragraph in paragraph in paragraph

Long lives the high ETM!

We have a long way to go

Device Physics rules!